

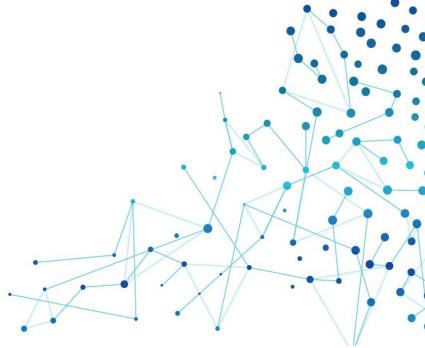
# Hailo-8 M.2 Al Acceleration Module

(NGFF M.2 2242/2260/2280 Key B+M Card)



Data Sheet

Rev 1.1 Spetember 2021



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## **Documentation Control**

## **Revision History**

| Version | Date              | Description                               |
|---------|-------------------|---|
| 0.1     | April 2021        | First release                             |
| 1.0     | April 2021        | Full access version                       |
| 1.1     | September<br>2021 | 4.2 – SW installation instruction revised |



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## 1. Overview

#### 1.1. Introduction

The Hailo-8 M.2 Al Acceleration Module (part number HM218B1C2LA), compatible with the NGFF/M.2 form factor, is targeted at artificial intelligence (Al) applications. It is a member of Hailo's comprehensive family of PCI Express (PCIe) based acceleration modules that meet industry standards for a range of form factors and performance objectives.

The module is based on the Hailo-8 AI processor and features a full PCIe Gen 3 2-lane interface (x2), which enables high throughput of input and output data.

As a PCIe device, the module can be used to perform real-time, low latency neural network inference, using PCIe for streaming input data and for streaming inference results.

#### 1.2. System Requirements

#### Hardware:

- CPU Architecture
  - x86 based; or
  - ARM aarch-64 based
- At least 1 available M.2 slot (either M keyed, Socket 3 type or B keyed, Socket 2 type, sometimes called NVME)

#### Software:

- Linux Ubuntu or other distributions
- Supported kernel versions: multiple, tested on Linux kernel versions 4.15.0-39-generic and 5.0.16-050016-generic.



## 1.3. System Level Block Diagram

The following block diagram illustrates the Hailo-8 M.2 Al Acceleration Module (HM218B1C2LA):

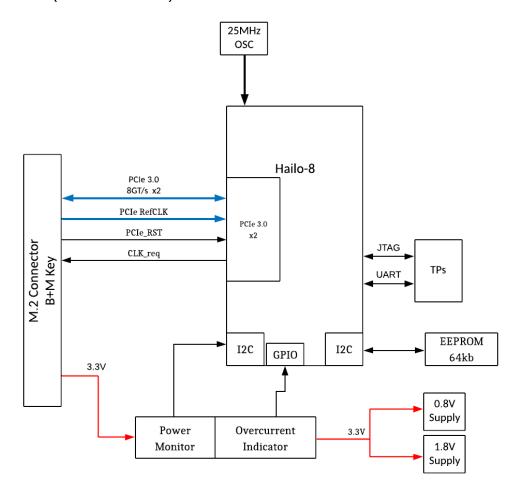


Figure 1: HM218B1C2LA Functional Block Diagram



## 2. Specifications

## 2.1. Key Properties

| Compliance                 |   |  |
|----------------------------|---|--|
| Certification              | CE; FCC Class A                                     |  |
| Environmental              |   |  |
| Storage Temperature        | 0°-70° C  |  |
| Operating Temperature      | 0°-70° C (refer to section 3.2 for further details) |  |
| Physical                   |   |  |
| Form Factor                | NGFF M.2 Key B+M                                    |  |
| Dimensions                 | 22 x 42 / 22 x 60 / 22 x 80 mm                      |  |
| Electrical                 |   |  |
| Power supply               | 3.3V ± 5%   |  |
| Thermal design power (TDP) | 8.65W   |  |
| Interface                  | PCIe Gen 3, 2-lanes (x2)                            |  |



#### 2.2. PCle Connector Pinout

| Pin Number(s)             | Signal         | Туре              |
|---------------------------|----------------|-------------------|
| 21                        | CONFIG_0 (GND) | Defines module    |
| 69                        | CONFIG_1 (NC)  | type:<br>SSD-PCle |
| 75                        | CONFIG_2 (GND) | 335 T CIC         |
| 1                         | CONFIG_3 (GND) |                   |
| 3,27,33,39,45,51,57,71,73 | GND            | Power             |
| 2,4,70,72,74              | 3.3V           | Power             |
| 50                        | PERST#         | 1                 |
| 52                        | CLKREQ#        | 1/0               |
| 54                        | PEWAKE#        | I/O               |
| 53,55                     | REFCLK[n/p]    | I                 |
| 41,43                     | PET[n/p]0      | 0                 |
| 47,49                     | PER[n/p]0      | I                 |
| 29,31                     | PET[n/p]1      | 0                 |
| 35,37                     | PER[n/p]1      | I                 |

Table 1: HM218B1C2LA Pin Description

For more information, see the *PCI Express M.2 Specification Revision 3.0* on the <u>PCISIG website</u>.

## 2.3. Mechanical Properties

Below is a mechanical outline for the HM218B1C2LA module. Note that



even though the module is a small form factor 22mm\*42mm (2242), it is provided with removable tabs to accommodate systems which only support 2260 or 2280 modules mechanically.

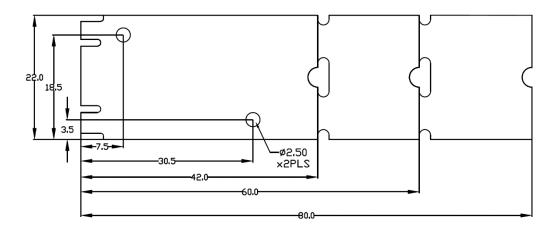


Figure 2: HM218B1C2LA Mechanical Outline (Top View)

For more information, see the *PCI Express M.2 Specification Revision 3.0, Version 1.2* on the <u>PCISIG website</u>.



# Power Consumption and Thermal Management

#### 3.1. Module Power Consumption

The module requires a 3.3V supply (power pins are as detailed in Table 1).

The module's power consumption is dependent on the resources utilized for inference. Maximum power consumption is 8.25W (or 2.5A total current draw from 3.3V pins) at full utilization.

The module's power consumption (typical at 25° C) is listed below for typical configurations:

| Configuration                   | Power [W] |
|---------------------------------|-----------|
| Resnet-50 224x224 @ 915 FPS     | 3.3       |
| MobileNet-SSD 300x300 @ 996 FPS | 2.4       |

Table 2 - Power Consumption for Typical Configurations

For up-to-date benchmark performance please visit the benchmarks page on Hailo's website.

## 3.2. Thermal Management Requirements

The HM218B1C2LA is tested and validated for commercial temperature grade ( $0^{\circ}$ C -  $70^{\circ}$ C) when mounted in a test fixture.

Proper heat dissipation must be employed to ensure that the Hailo-8 chip does not overheat. The Hailo-8 is designed to dissipate most of the



heat to the top surface of the package.

For more information on typical use configurations and design guidelines, see Hailo's *Hailo-8 Al Acceleration Module Thermal Design Considerations Application Note*.

#### 3.3. Overheat and Overcurrent Protection

The module features monitoring and protection from overheat conditions and excessive power consumption. The following features are supported:

**TBD** 

For additional information on thermal design, see sec. 3.2.

For more information on power consumption limits, see the *PCI Express M.2 Specification Revision 3.0* on the <u>PCISIG website</u>.



## 4. Installation and Troubleshooting

#### 4.1. Hardware Installation

- 1. Make sure that the host computer is turned off.
- 2. Firmly attach the M.2 module into a proper M.2 slot (make sure it is either M keyed, Socket 3 type or B keyed, Socket 2 type).
- 3. Power up the computer and log on to Linux.
- 4. Verify that the Hailo-8 is detected on the PCle bus. From a Linux terminal, type:

```
>> lspci | grep "Co-processor: Hailo Technologies Ltd. Hailo-8 AI Processor (rev 01)"
```

#### 4.2. Software Installation

1. Power up the computer and log on to Linux.

The HailoRT package includes 3 files:

- platform.tar.gz Archive of the HailoRT binaries and Python modules.
- install.sh Installation script.
- md5s.txt MD5 hashes of the HailoRT files.
- 2. Run the following command to install HailoRT including the PCIe driver:

```
>> chmod u+x install.sh
>> ./install.sh
```



3. Reboot the machine after the installation is done. The driver will be loaded automatically after reboot. Run the

following commands in order to verify it:

Start the Hailo-RT virtual environment. From a Linux terminal type, at the location where the Hailo-RT package was installed:

```
>> source hailo_virtualenv/bin/activate
>> hailo scan
```

The hailo scan command should identify the device.

For further information and instructions, see *Running HailoRT installation* in the HailoRT User Guide.



## 4.3. Troubleshooting

| A. Improper PCIe device enumeration |  |
|-------------------------------------|--|
| How to verify:                      | From a Linux terminal type:  |
|                                     | <pre>&gt;&gt; lspci   grep "Co-processor: Hailo Technologies Ltd. Hailo-8 AI Processor (rev 01)"</pre> |
|                                     | The device should be listed in the terminal output   |
|                                     |  |
| Possible root cause:                | Improper mechanical installation   |
| Solution:                           | Verify the module is properly attached and secured into the M.2 slot.                                  |
|                                     |  |
| Possible root cause:                | Slot is not functional   |
| Solution:                           | Verify the slot in use is a valid M.2 slot (either M   |
|                                     | keyed, Socket 3 type or B keyed, Socket 2 type).   |
|                                     | Check to see if the slot is disabled in platform BIOS.   |

## B. Device driver not properly installed



| How to verify:       | From a Linux terminal type:   |
|----------------------|---|
|                      | >> lsmod   grep <tbd></tbd>   |
|                      | The device should be listed in the terminal output  |
|                      |   |
| Possible root cause: | Driver not installed  |
| Solution:            | Obtain the driver installation package provided by Hailo and follows SW installation instructions (section 4.2) |

| C. Module not identified by Hailo-RT |  |
|--------------------------------------|--|
| How to verify:                       | <pre>From a python shell type:  &gt;&gt; from hailo_platform.drivers.hw_object import HailoPcieObject  &gt;&gt; p = HailoPcieObject()  &gt;&gt; p.control.identify()</pre> |
|                                      | The device should be listed in the interpreter output  |
|                                      |  |
| Possible root cause:                 | Improper installation of the Hailo-RT package  |



| Solution: | Re-install the Hailo-RT package by following the |
|-----------|--|
|           | installation instructions.                       |